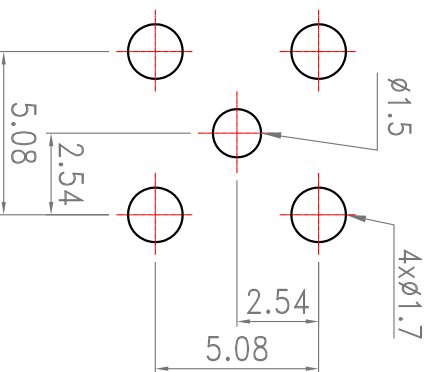
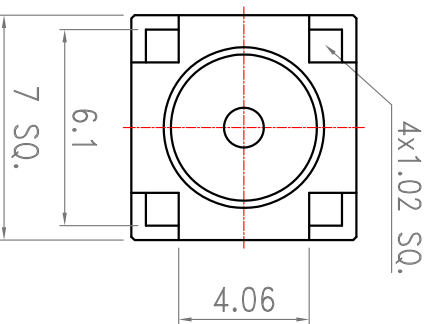
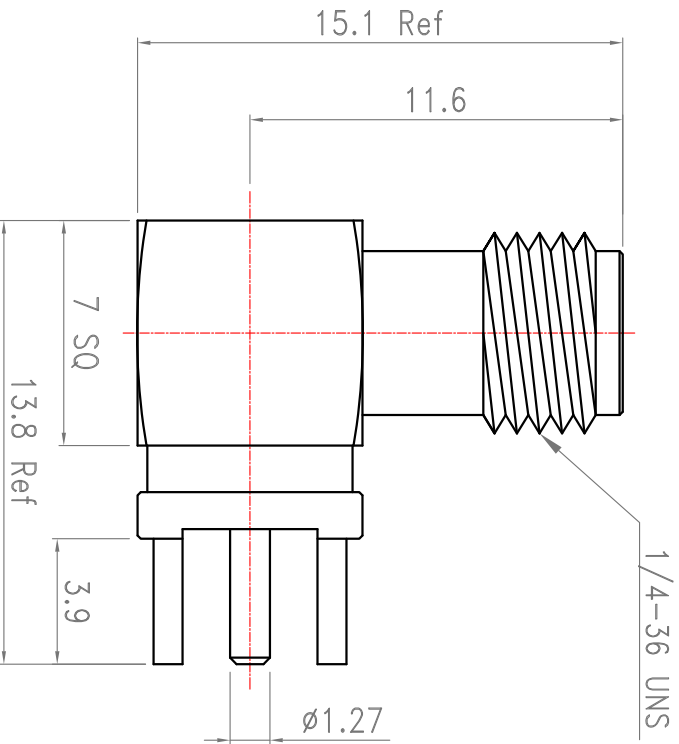


Revisions

Note: Revisions B: B-1; B-2..... On behalf of official Drawing.
 Revisions 1; 2; 3; 4..... On behalf of experiment's Drawing.

| ISS | Symbol | Description | Date |
|-----|--------|---|------------|
| B | | CHE for New Drawing Frame & New PN System | 2006/07/11 |

Outline Drawing



Recommended PCB Layout

| ITEM | Description | Material | Finish | Part Number | QTY |
|------|-------------|----------|----------|-------------|-----|
| 6 | | | | | |
| 5 | | | | | |
| 4 | | | | | |
| 3 | Pin | BeCu | 30u"Gold | | |
| 2 | Insulator | PTFE | None | | |
| 1 | Body | Brass | Gold | | |

| Scale | Abbr. | Date | Rev. |
|-------|-------|------------|------|
| NTS | ST | 2011/04/28 | B |

| DWG. NO. | TITLE |
|-----------|------------------------|
| W50110005 | SMA R/A Jack, PCB Type |

Customer P/N:

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 Material All Procurement

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